



Connectors > Card & Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Single Data Rate (M3)**

Connector System: **Board-to-Board**

Number of Positions: **90**

PCB Mounting Style: **Surface Mount**

Module Orientation: **Vertical**

Features

Product Type Features

DRAM Type	Single Data Rate (M3)
Connector System	Board-to-Board
Row-to-Row Spacing	1.6 mm[.06 in]
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket
Profile	Standard

Configuration Features

Center Key	Offset Left
Number of Keys	1
Number of Bays	2
Number of Positions	90
Module Orientation	Vertical
Number of Rows	2

Body Features

Ejector Material Color	Silver
Retention Post Material	Stainless Steel
Ejector Material	High Temperature Thermoplastic
Ejector Location	Left End Only
Module Key Type	Offset Right



Retention Post Location	None
Ejector Type	Locking

Contact Features

Socket Style	DIMM
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold
Solder Tail Contact Plating Thickness	3 µm[118.1 µin]
Socket Type	Memory Card

Termination Features

Insertion Style	Cam-In
Termination Post Length	2.6 mm[.0826 in]

Mechanical Attachment

Polarization	Left
Locating Posts	Without
PCB Mount Retention	With
PCB Mount Retention Type	Boardlock
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount
Boardlock Material	Stainless Steel
Mounting Angle	Vertical

Housing Features

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	Thermoplastic
Housing Color	Gray

Dimensions

Height Above PC Board	30.4 mm[1.19 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application



Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Box & Tray, Tray
Packaging Quantity	80

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2019 (197) Candidate List Declared Against: JAN 2018 (181)
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

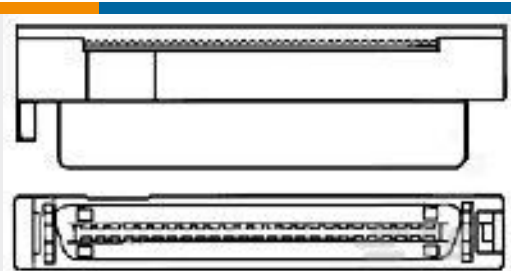
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE’s information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) ‘Guidance on requirements for substances in articles’(Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of ‘complex object’, the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA “Guidance on requirements for substances in articles” (June 2017, version 4.0) and will be updating its statements accordingly.

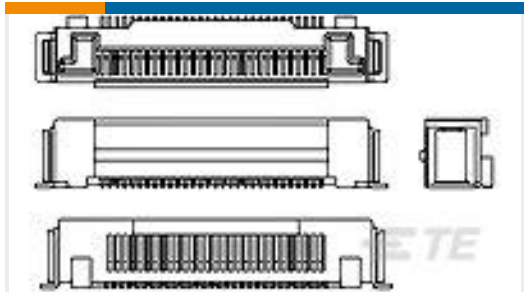
Customers Also Bought

MIII (V) GRAY

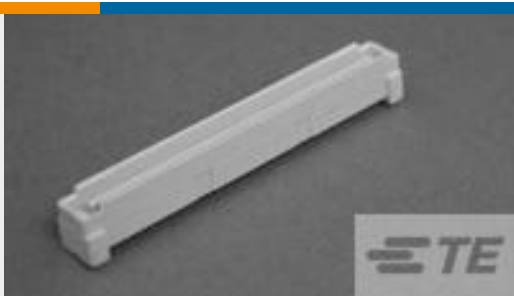
TE Part # 6376118-6
TE Internal #: 6376118-6



TE Part #5178647-4
CHAMP 050 B-T-B REC
HDR ASSY H



TE Part #2013790-1
FPC EASY MATING
CONN.,0.5mm/REC ASSY
(V)



TE Part #4-5179230-5
0.8FH,P07H.5,120,08/Sn,
TU,SC



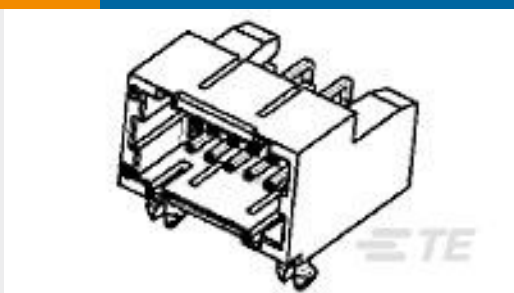
TE Part #5-292207-4
MINI CT SGL DIP V 4P
BLUE



TE Part #6376118-1
MIII SOCKET (V)



TE Part #1-1318126-1
V-HDR ASSY 12P FOR
SEQUENTIAL TYPE



TE Part #3-292262-4
DBL ROW (H) DIP TYPE
WITH BOAR



TE Part #3-917946-1
2.0 AF REC ASSY 30P
EMBOSS ASS



TE Part #5-292207-8
MINI CT SGL DIP V 8P
BLUE



TE Part #6376118-2
MIII (V) BLACK

Documents

Product Drawings
MIII (V) GRAY

English

CAD Files

Customer View Model
ENG_CVM_6376118-6_O.2d_dxf.zip

English

Customer View Model
ENG_CVM_6376118-6_O.3d_igs.zip

English

Customer View Model
ENG_CVM_6376118-6_O.3d_stp.zip

English

3D PDF

English